



RE470

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Pitch 0.40 mm (15.7mil) and 0.50 mm (19.7 mil.)
- Adaption board for 23 different SMD-QFP s
- Hole diameter 1.00 mm
- Prescratched rated break point for the separation of individual modules from the board
- Gerber data for manufacture of the solder resist masks and the soldering paste imprint will be provided free of charge on request
- Size 132 x 203 mm

Module-No.	Pitch	Pin	mil	Size (mm)
RE470-01	S 0.500 mm	QFP 40, 48	19.7	7.00 x 7.00
	S 0.400 mm	QFP 80	15.7	10,00 x 10,00
RE470-02	S 0.500 mm	QFP 80	19.7	12,00 x 12,00
	S 0.400 mm	QFP 100, 108	15.7	12,00 x 12,00
RE470-03	R 0.500 mm	QFP 120, 128	19.7	14,00 x 20,00
	R 0.400 mm	QFP 100, 108	15.7	10,00 x 14,00
RE470-04	S 0.500 mm	QFP 72, 100	19.7	10,00 x 10,00
	S 0.400 mm	QFP 12	15.7	14,00 x 14,00
RE470-05	S 0.500 mm	QFP 144, 176	19.7	20,00 x 20,00, 24,00 x 24,00
	S 0.400 mm	QFP 184	15.7	20,00 x 20,00
RE470-06	R 0.500 mm	QFP 256, 264	19.7	28,00 x 40,00
	R 0.400 mm	QFP 224, 232	15.7	20,00 x 28,00
RE470-07	S 0.500 mm	QFP 208, 240	19.7	28,00 x 28,00, 32,00 x 32,00
	S 0.400 mm	QFP 264	15.7	28,00 x 28,00